

Intel® Embedded Development Board Mini-ITX Carrier

**Carrier Board Schematics supporting Intel® Embedded
Development Board Compute Modules**

January 2011

Revision 001



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Revision History

Document Number	Revision Number	Description	Revision Date
324768	001	Initial release.	January 2011

INTEL CORPORATION

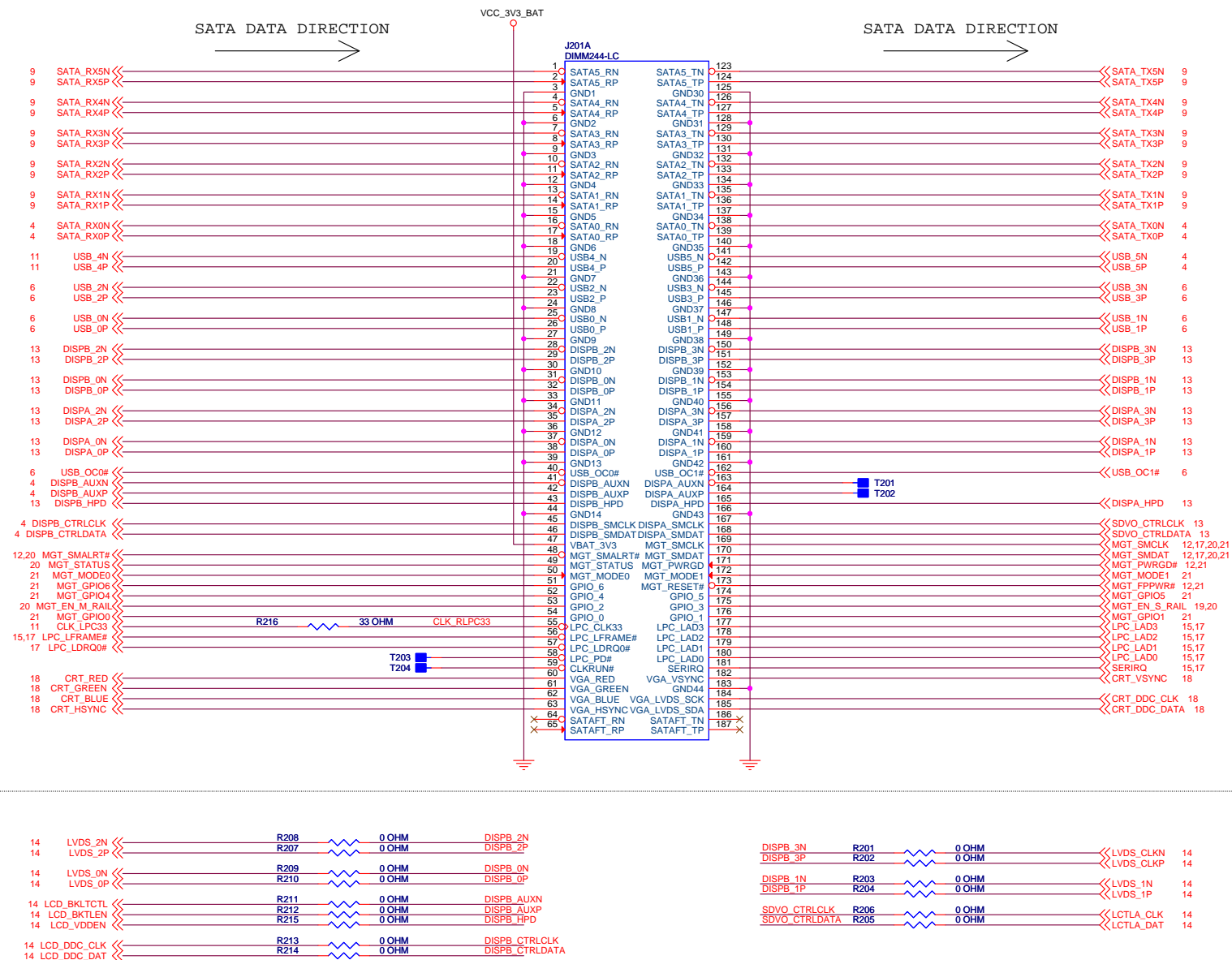
Embedded & Communications Group

Intel® Embedded Development Board -Mini-ITX Carrier Schematics - Revision: B

Note: Development Boards will be marked with Viking Modular Solutions*

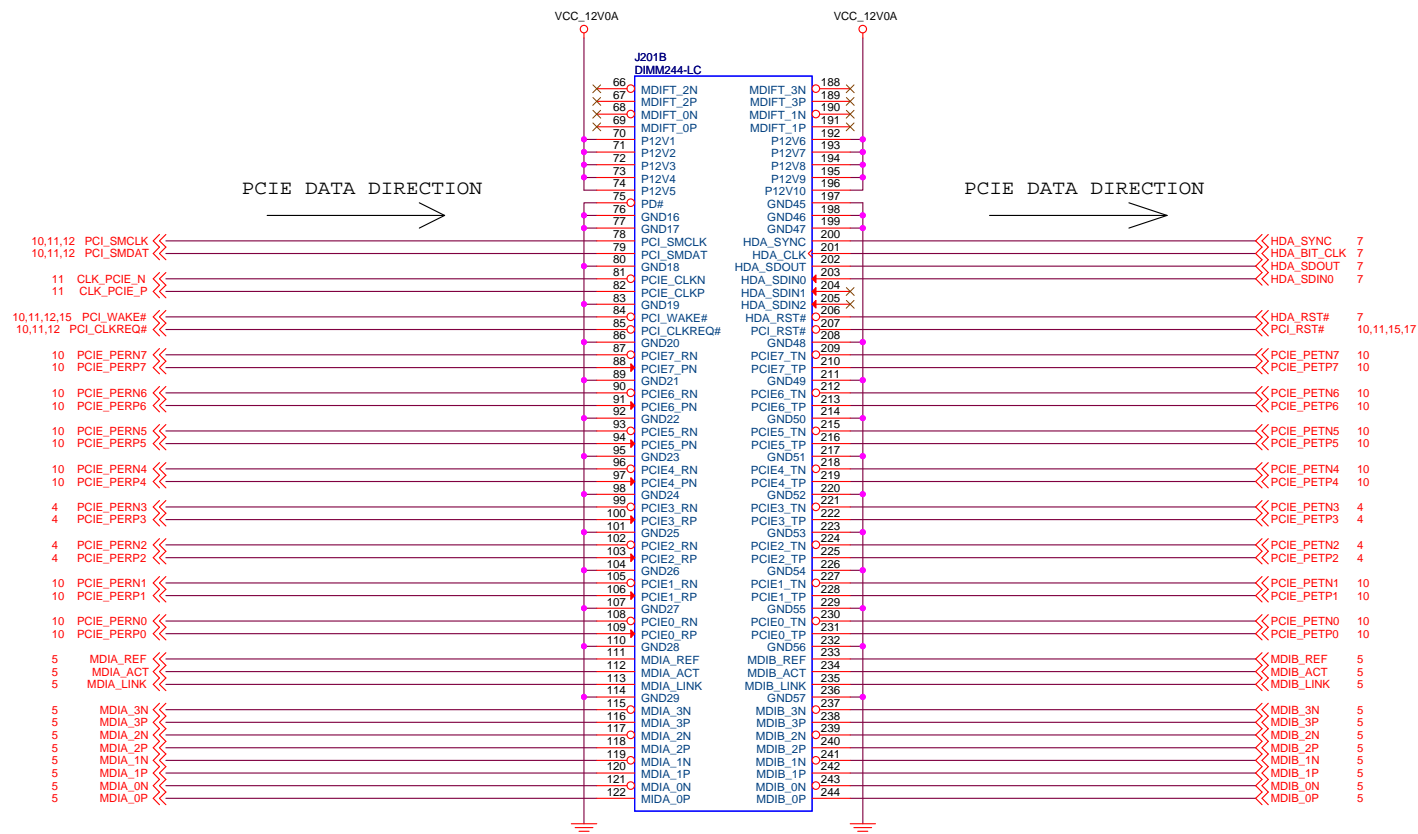
EMP-CAI-CAP-IAG-Intel

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ITX Carrier Schematics		
Size	Document Number	Rev
	324768	B2
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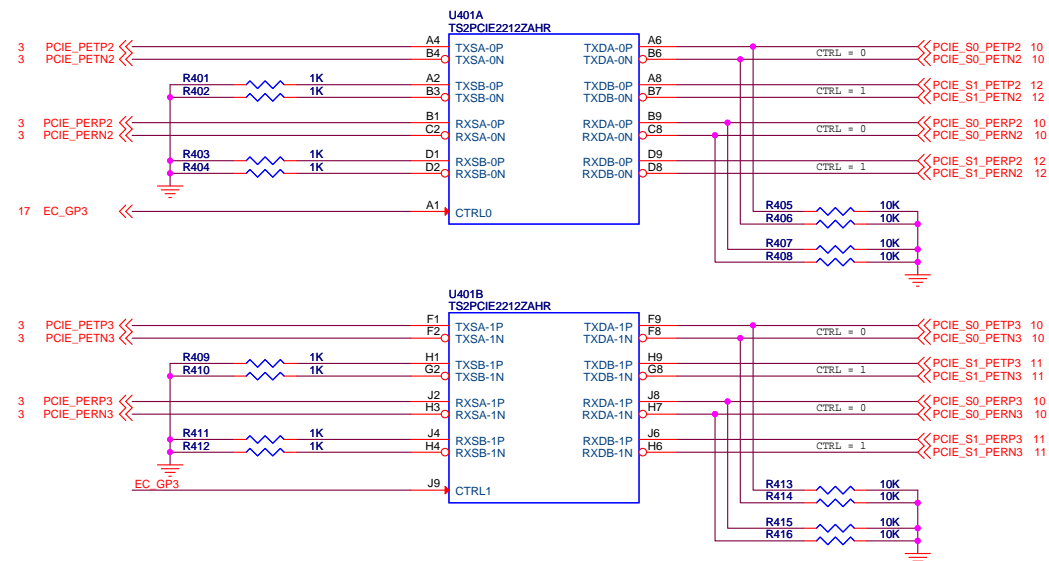
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Size	Document Number	Rev
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Date:	Thursday, January 27, 2011	Sheet 2 of 21

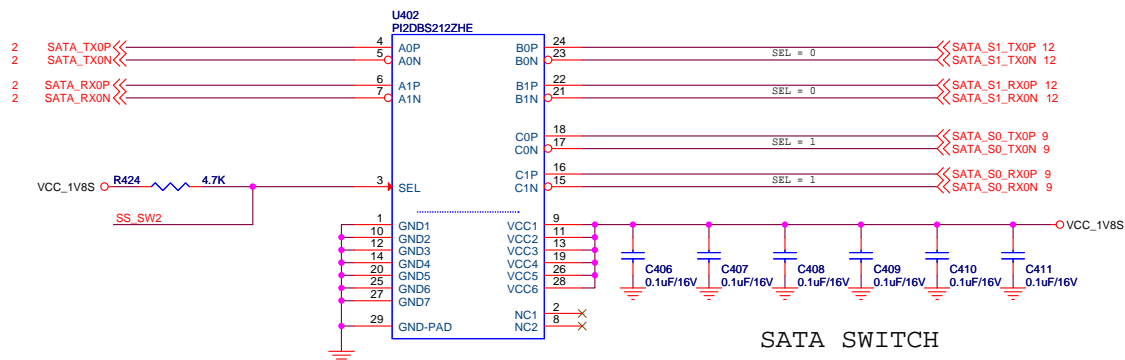


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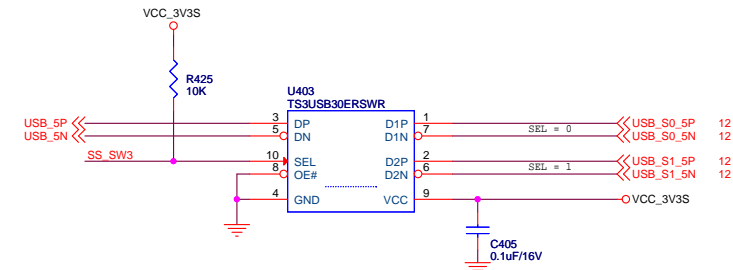
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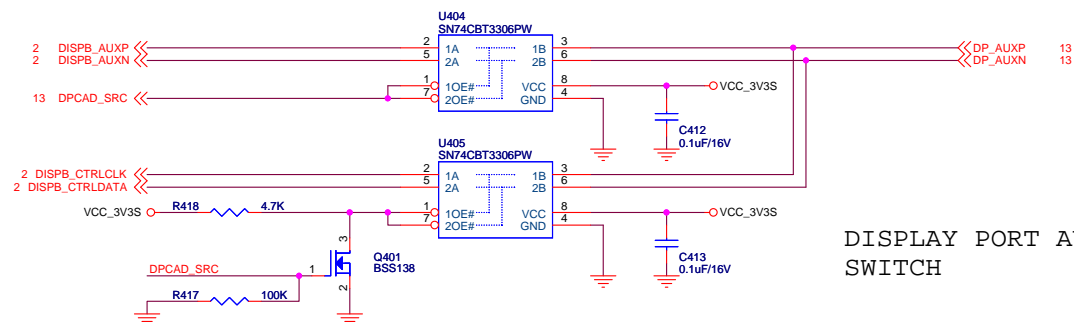
PCI EXPRESS SWITCH



SATA SWITCH

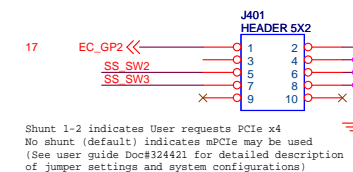


USB SWITCH



DISPLAY PORT AUX SWITCH

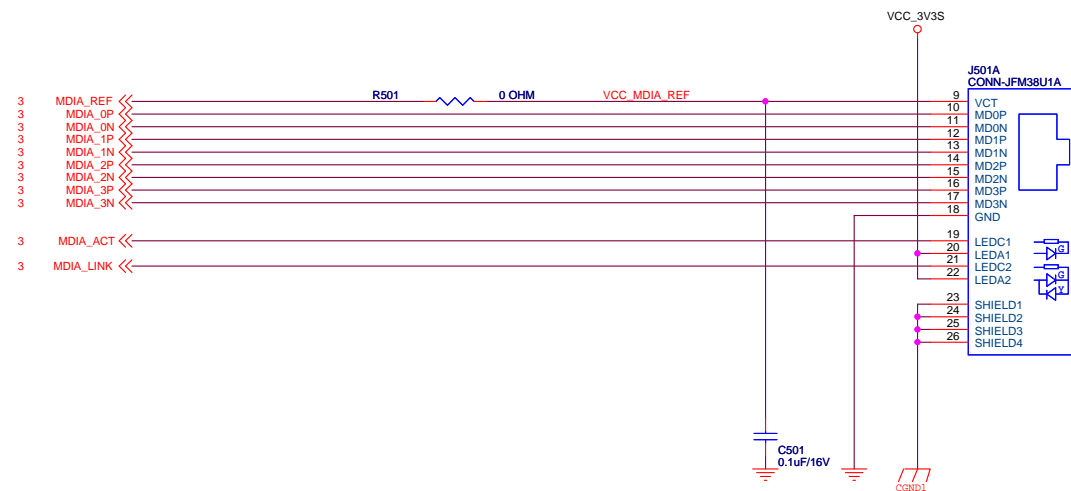
SWITCH SELECT JUMPER



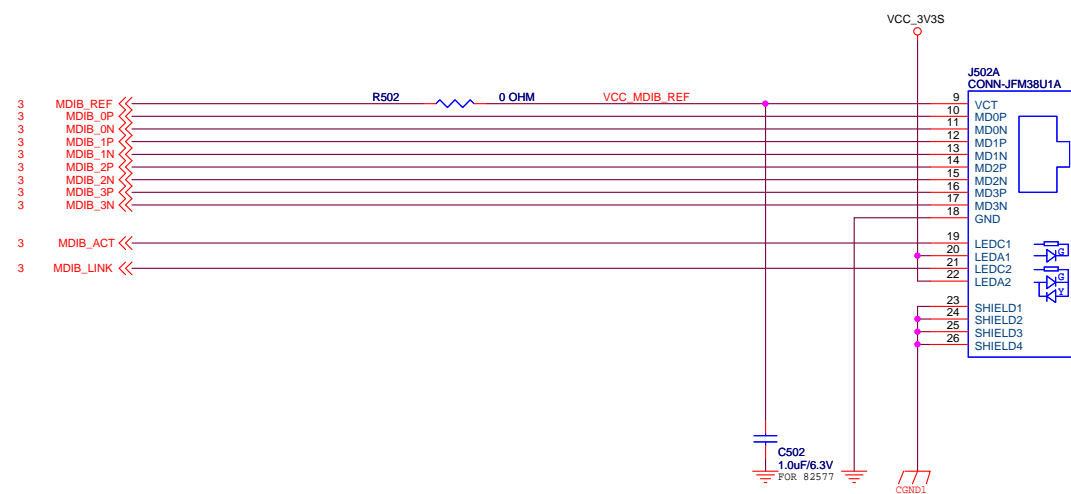
Shunt 1-2 indicates User requests PCIe x4
 No shunt (default) indicates mPCIe may be used
 (See user guide Doc8324421 for detailed description
 of jumper settings and system configurations)

EMP-CAI-CAP-IAQ-Intel

Title		
Switches		
Size	Document Number	Rev
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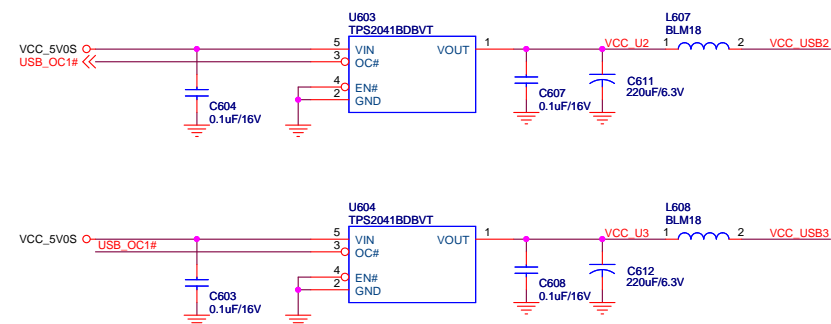
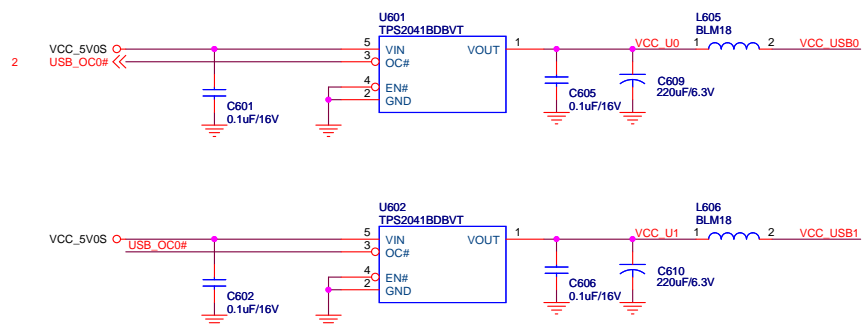
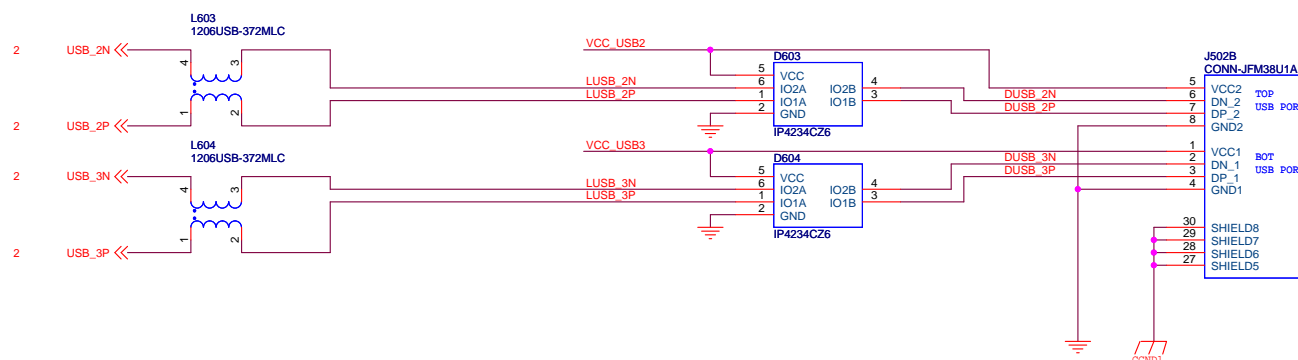
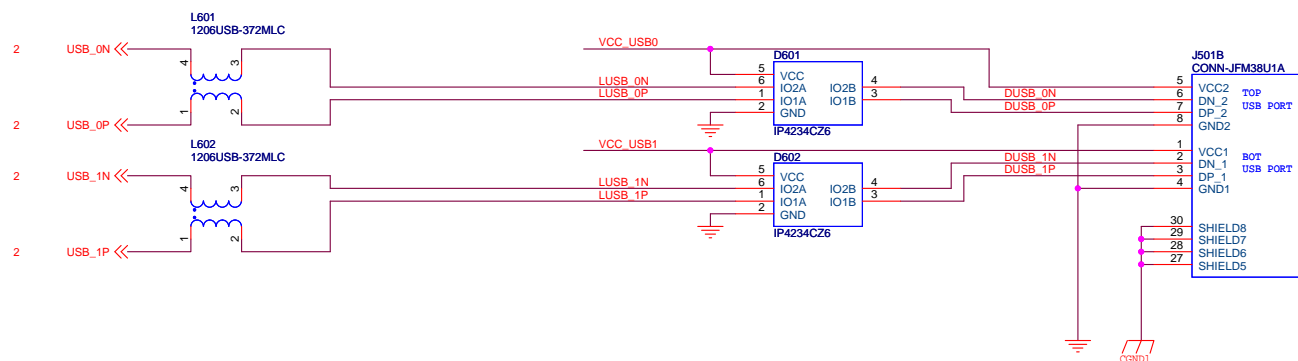


Reference Design Note:
Selected RJ-45 jacks include integrated Magnetics
and must be supported by the MAC/Phy on the
compute module per supplier design guidelines.



EMP-CAI-CAP-IAG-Intel

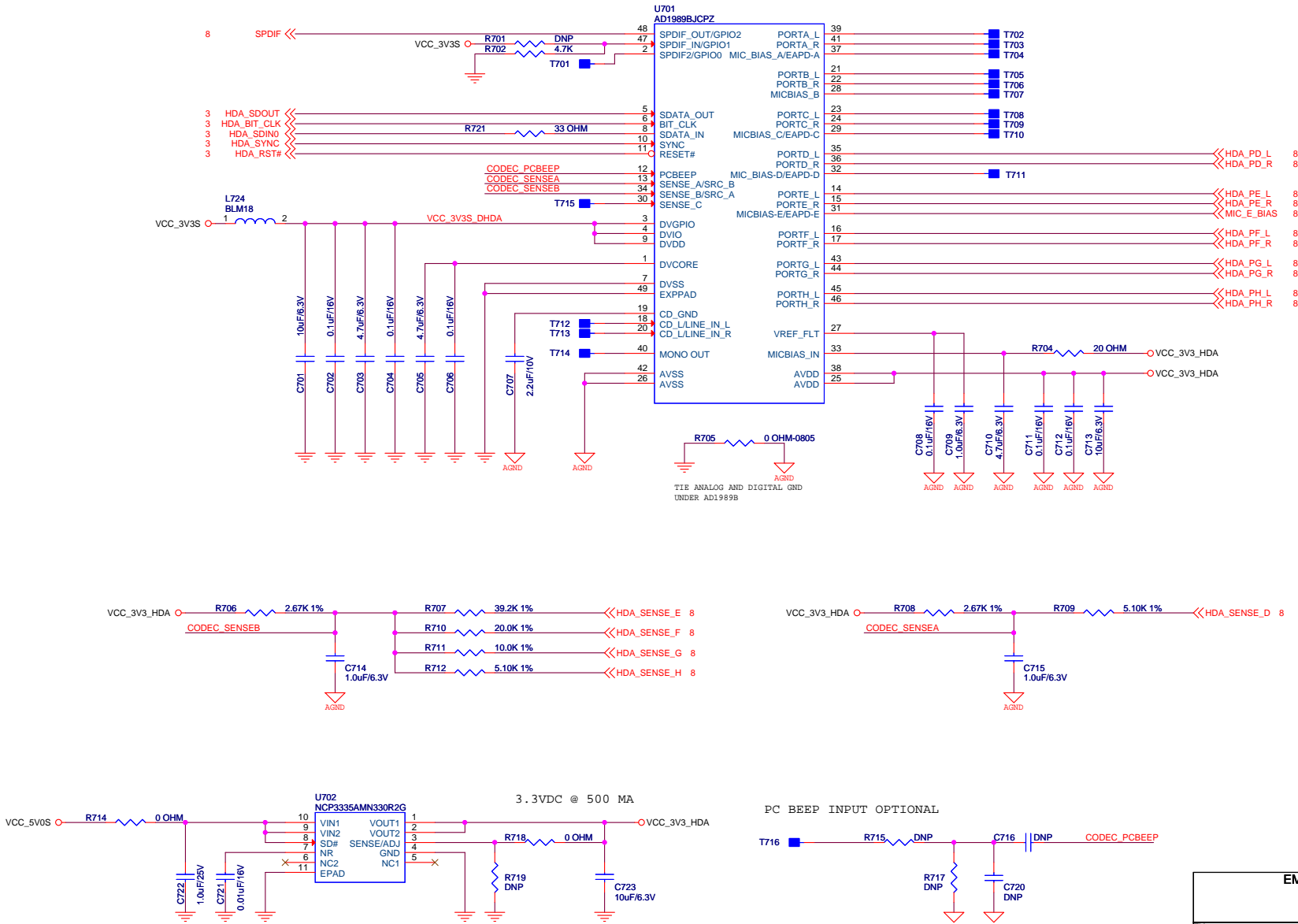
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Size	Document Number	Rev
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EMP-CAI-CAP-IAG-Intel

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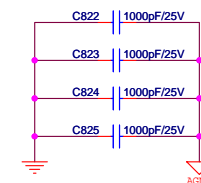
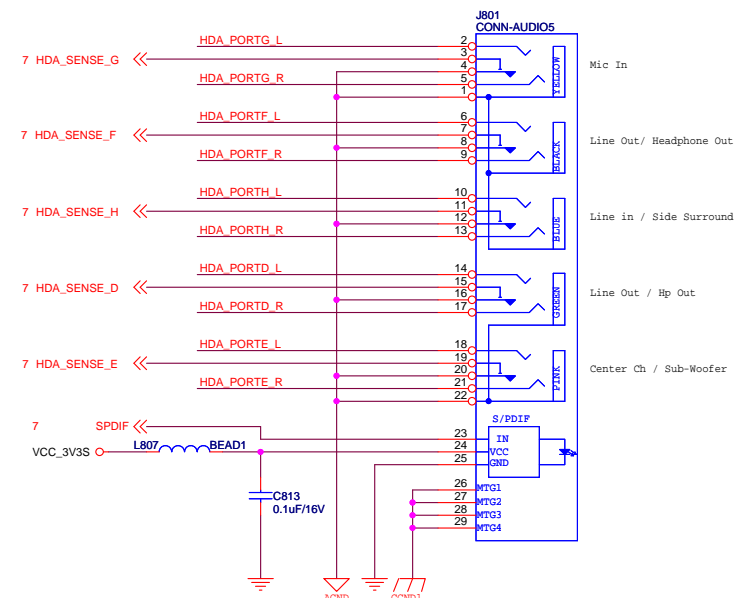
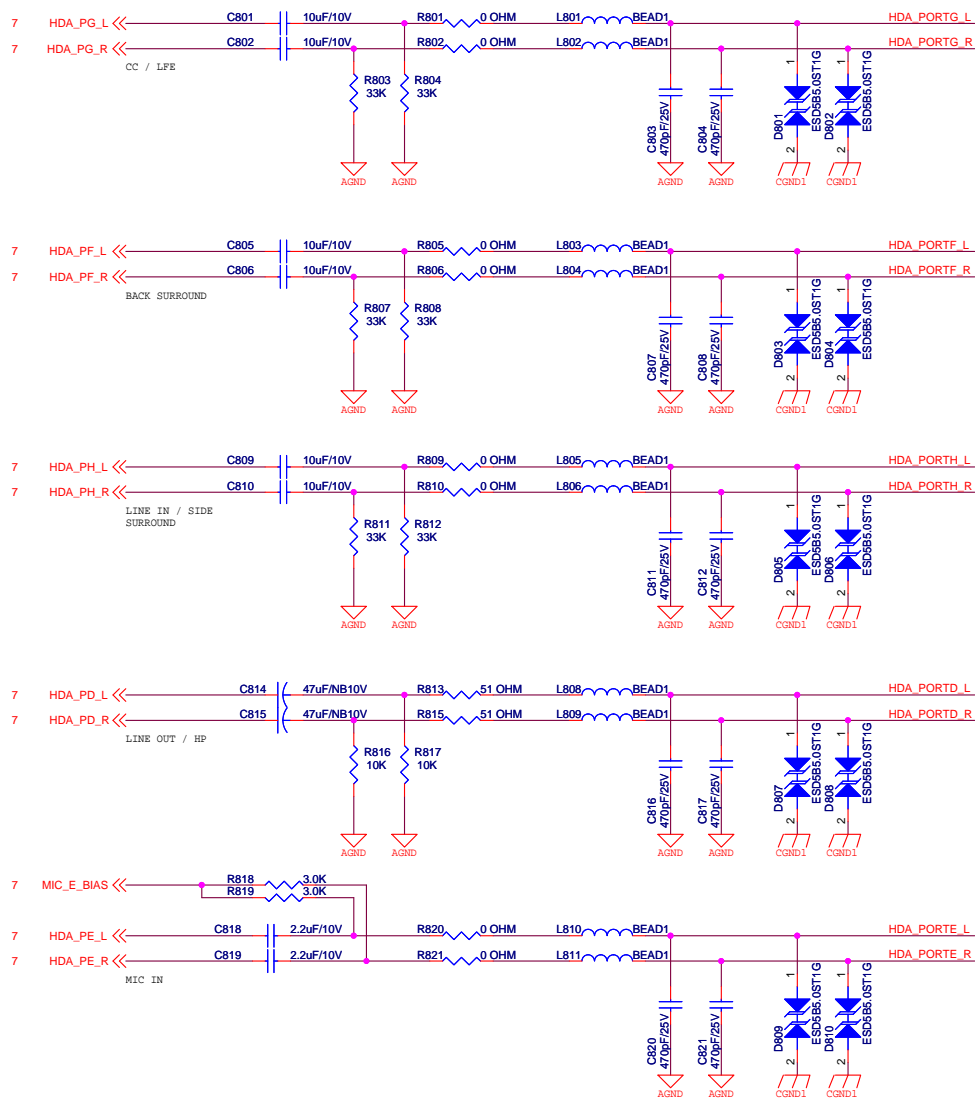
7.1 SURROUND HIGH DEFINITION AUDIO CODEC



EMP-CAI-CAP-IAG-Intel		
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HD Audio Codec		
Size	Document Number	Rev
324768		B2
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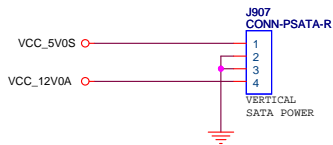
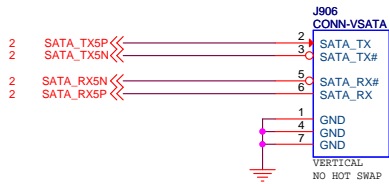
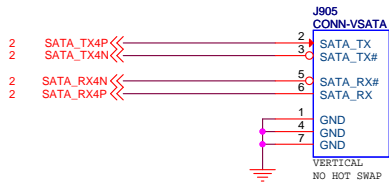
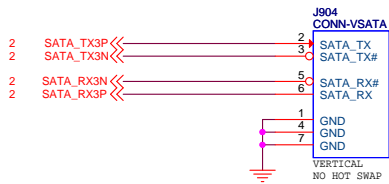
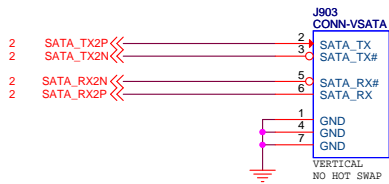
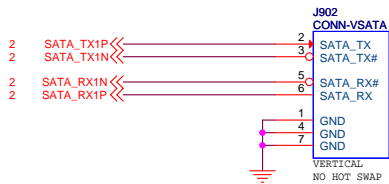
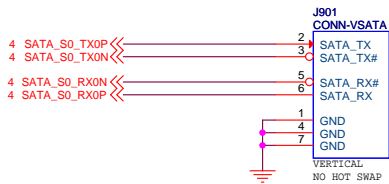
HD AUDIO CONNECTORS

Note: Mapping of HD Audio Function to Colors does not follow typical PC mapping - See color notes below



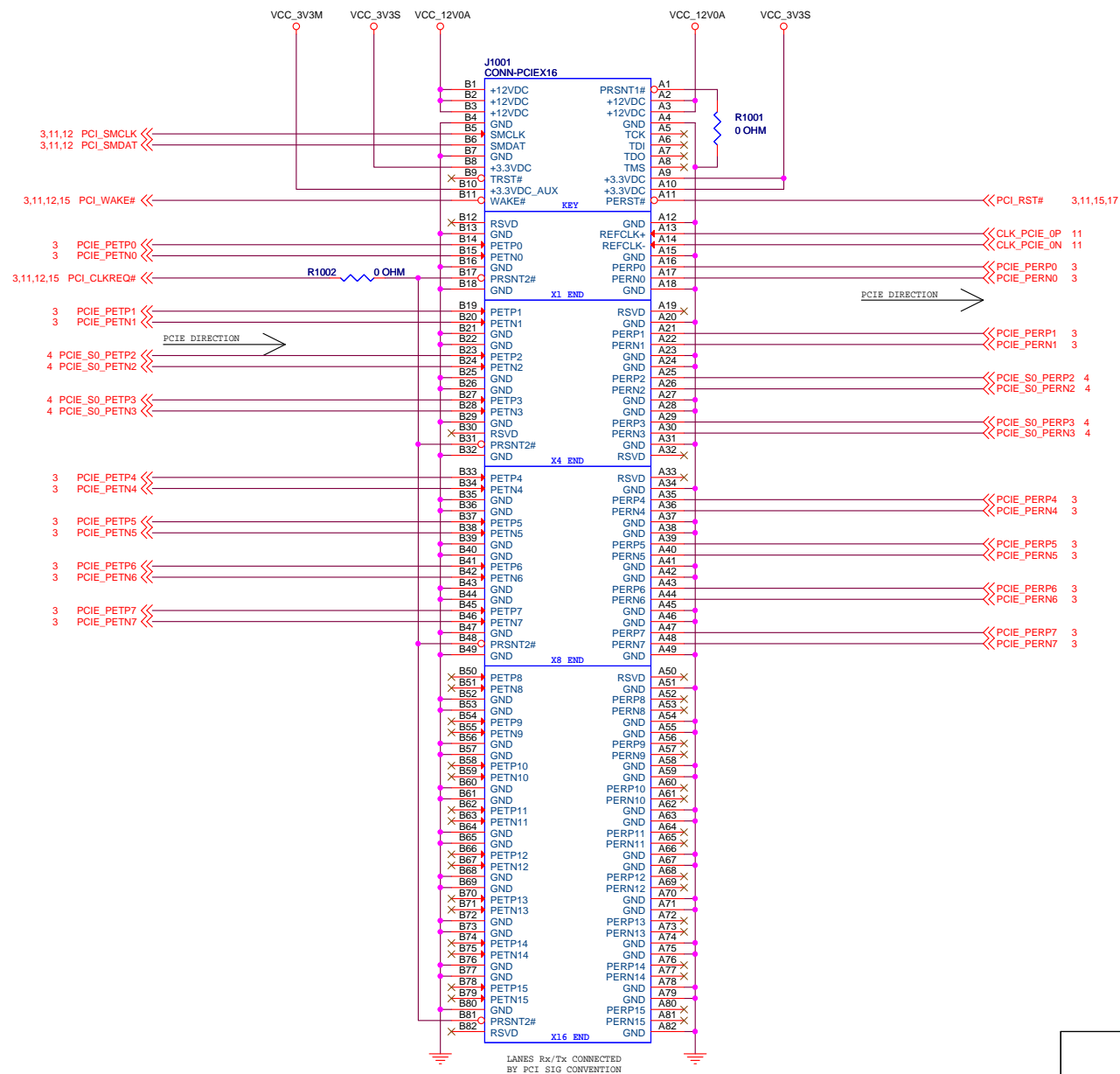
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Size	Document Number	Rev
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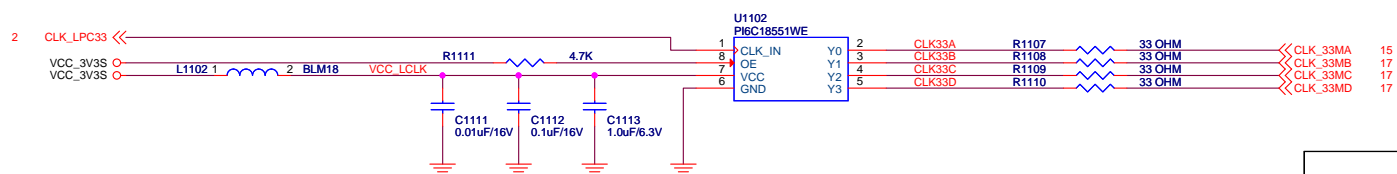
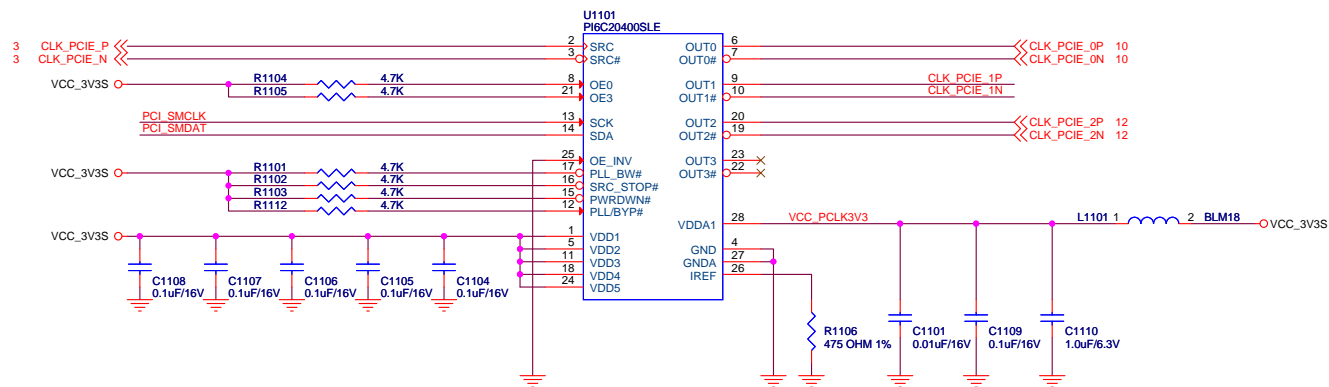
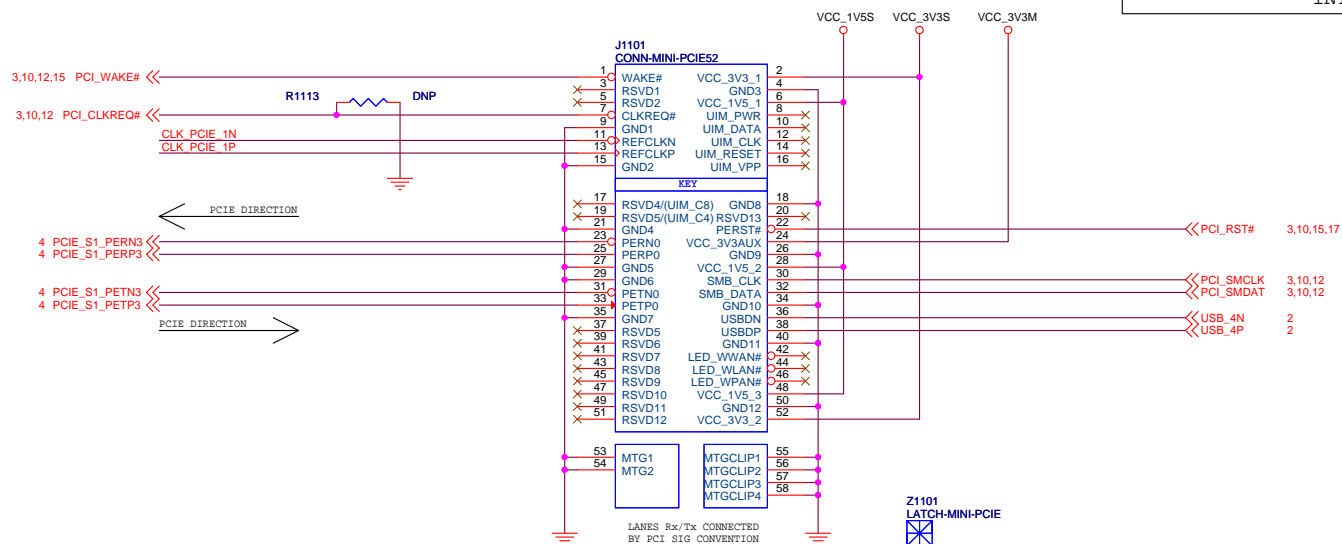
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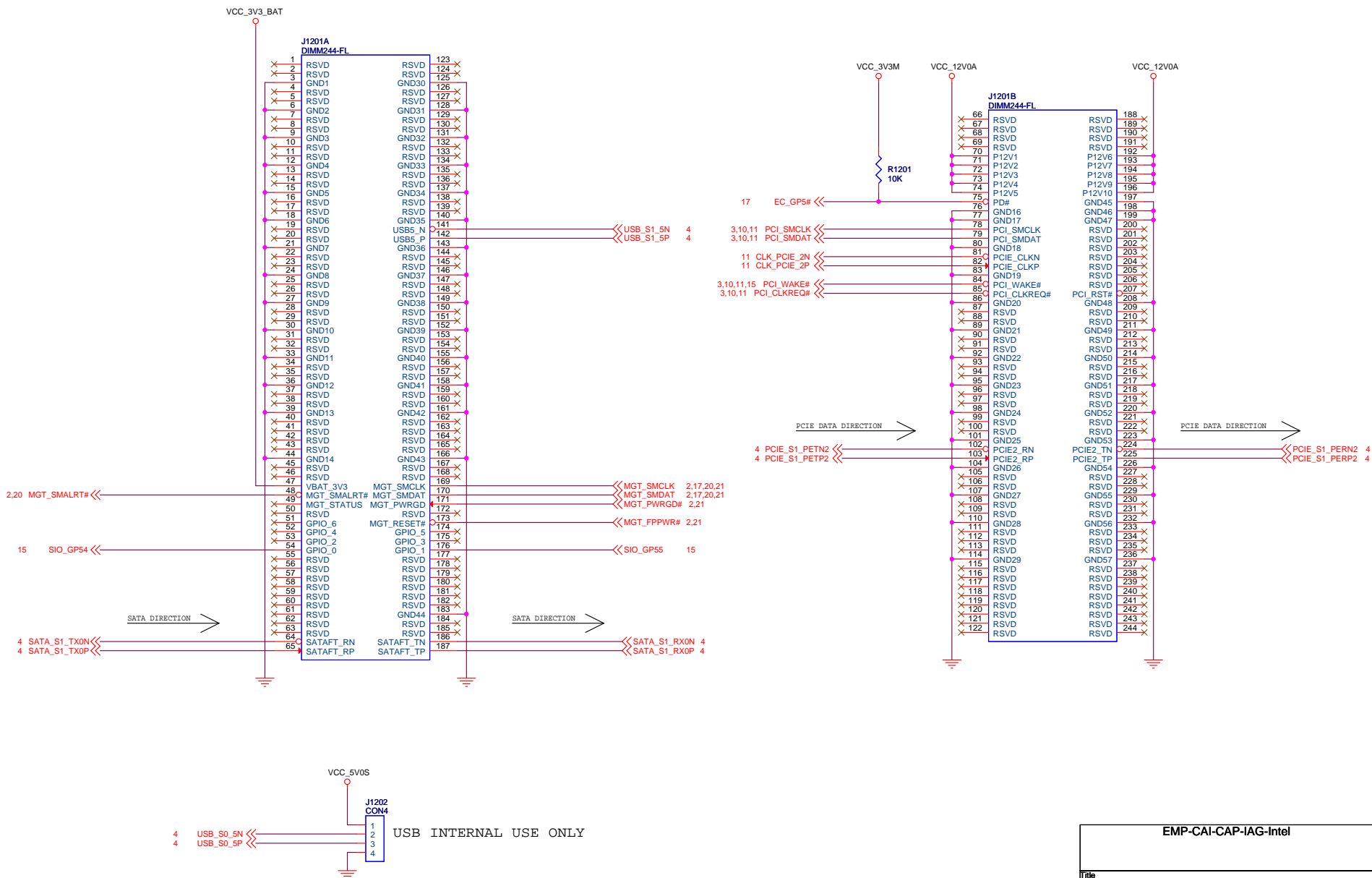
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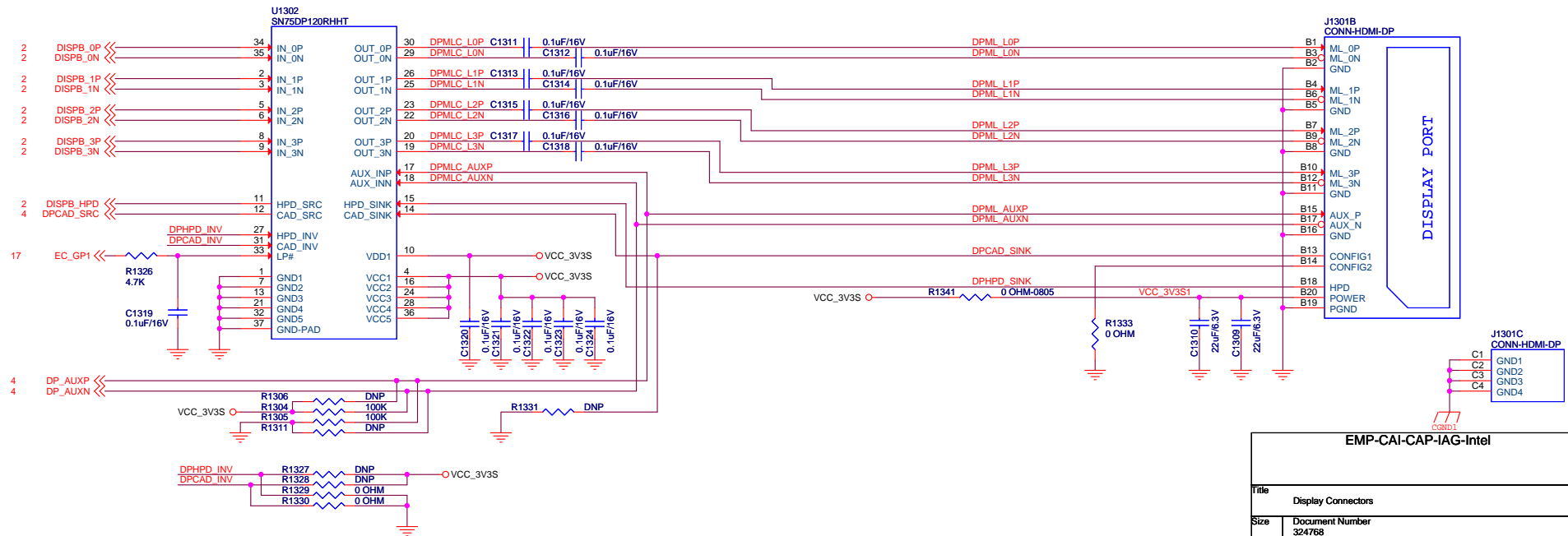
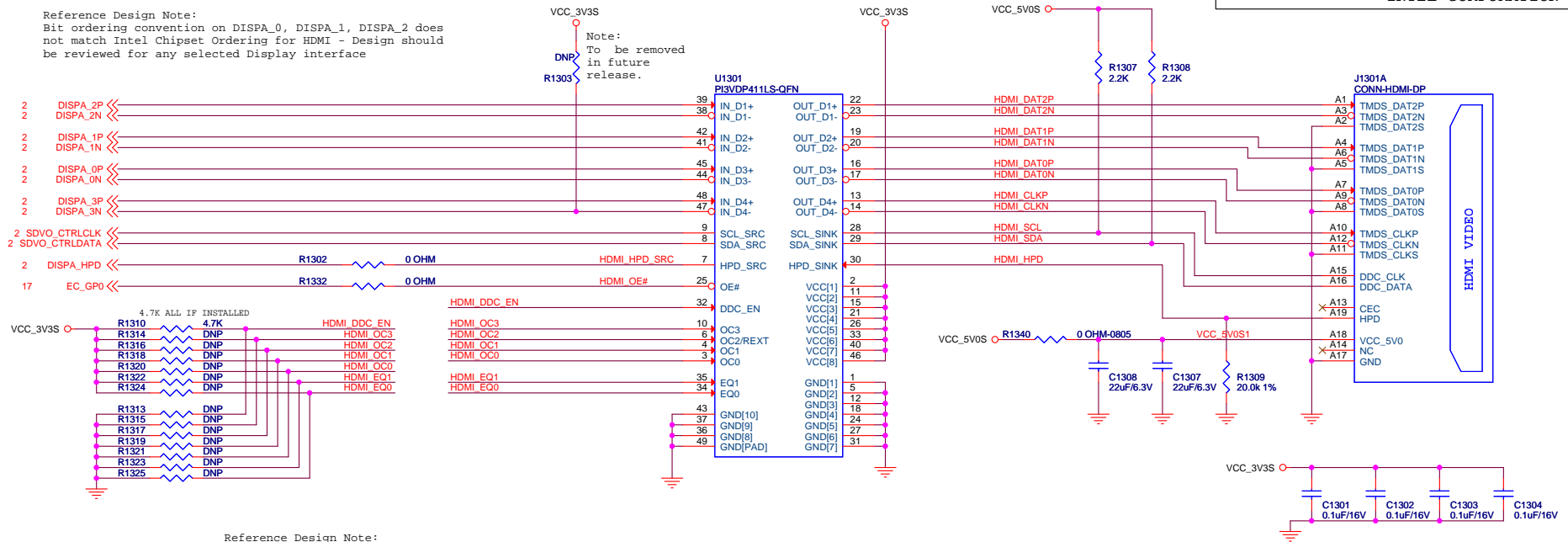
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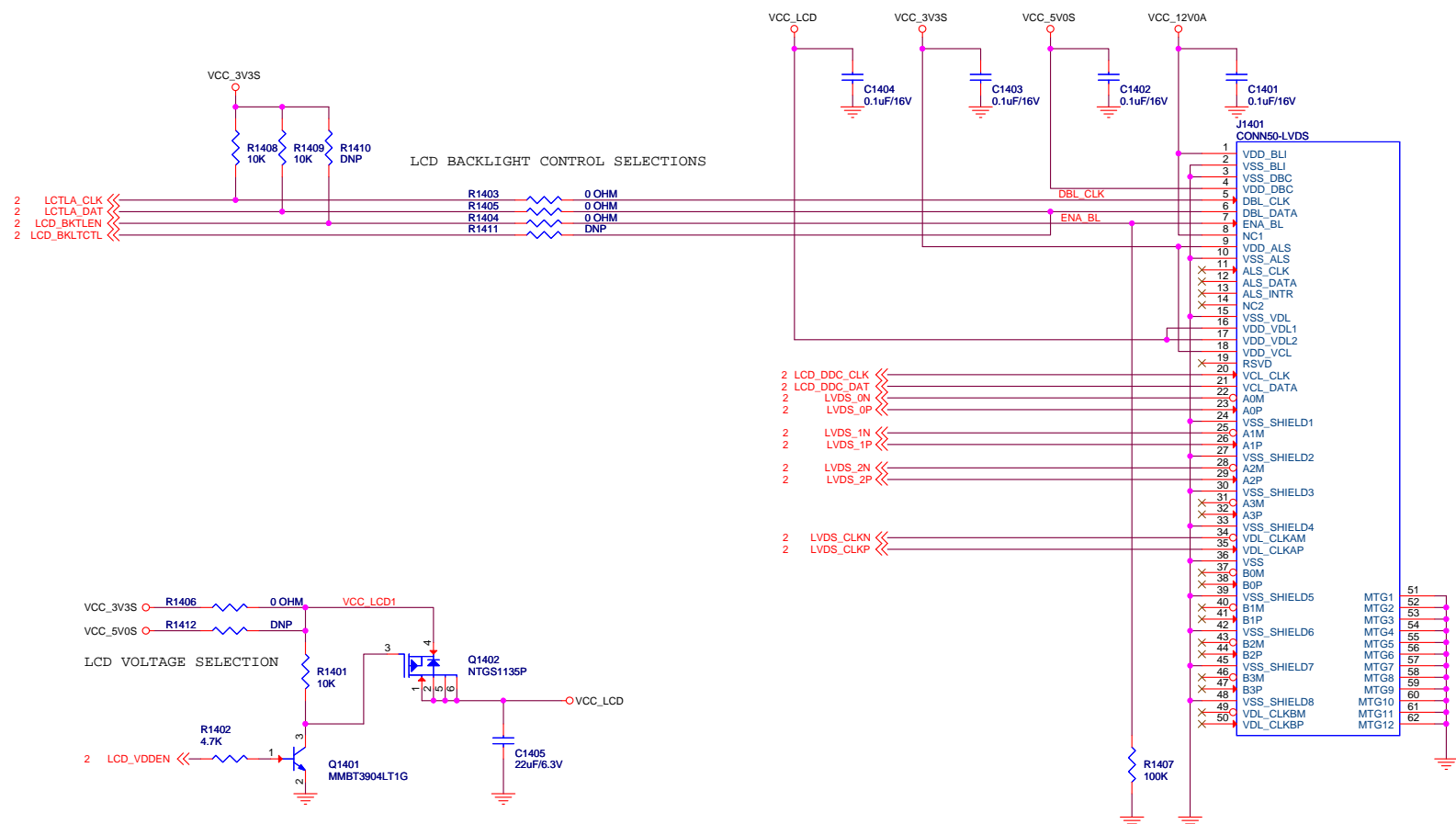
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Mini PCIe, CLK		
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Reference Design Note:

Bit ordering convention on DISPA_0, DISPA_1, DISPA_2 does not match Intel Chipset Ordering for HDMI - Design should be reviewed for any selected Display interface



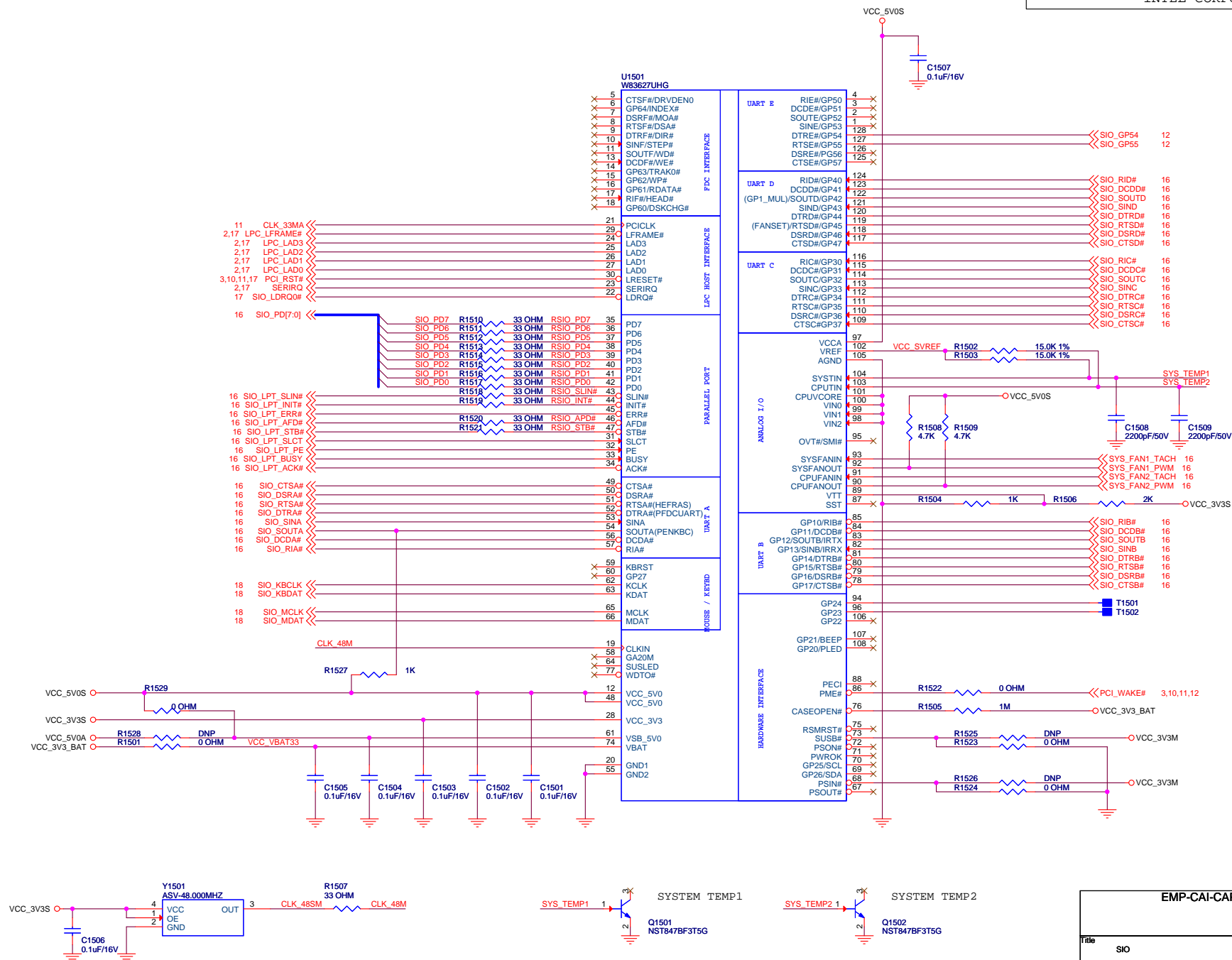


Note: No standard configuration has been defined for LVDS Panel Interfaces.
Care should be taken to validate correct signal compatibility with any LVDS cable
and panel before connection to this platform.

LVDS DISPLAY

EMP-CAI-CAP-IAG-Intel

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LVDS		
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INTEL CORPORATION

RS232 COMMUNICATIONS

FAN CONNECTORS

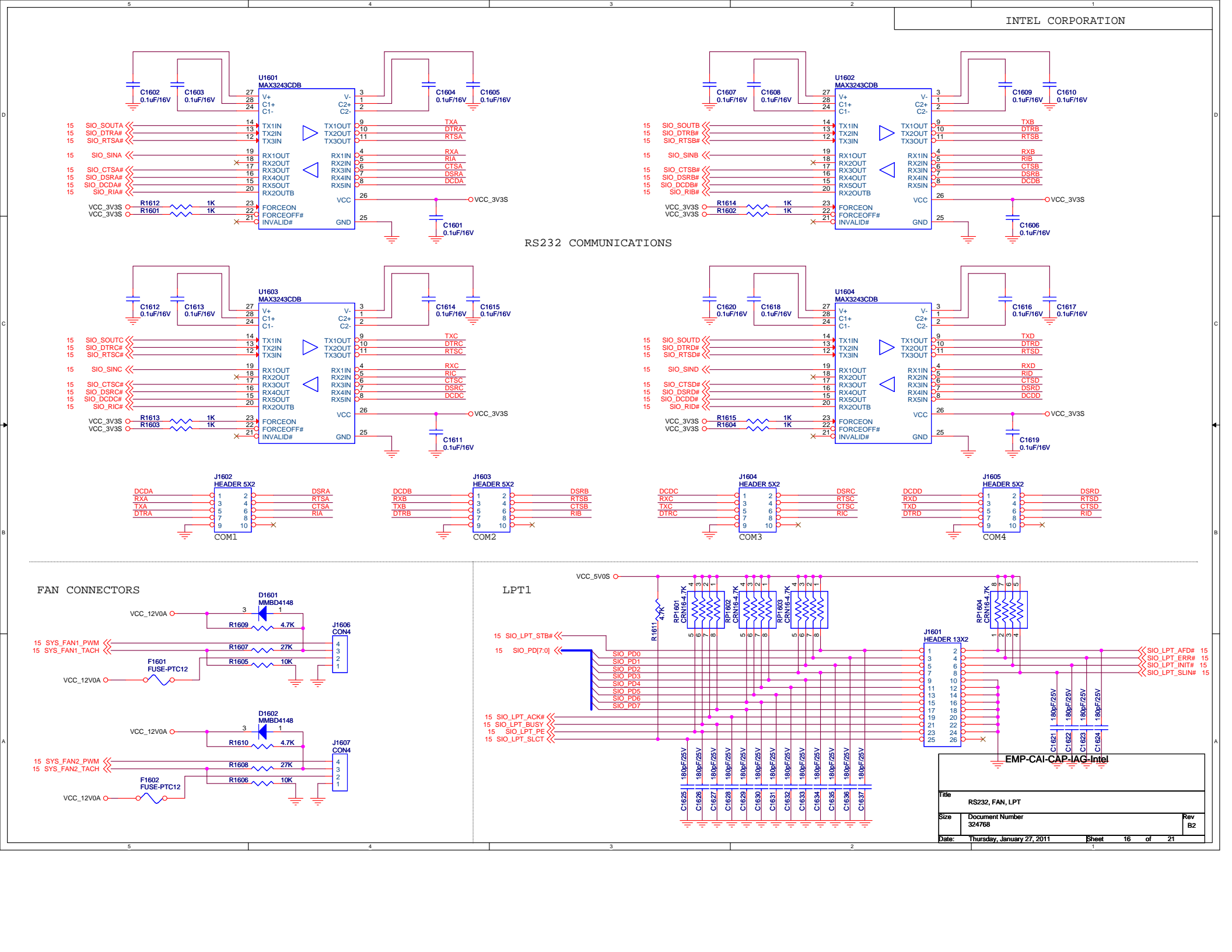
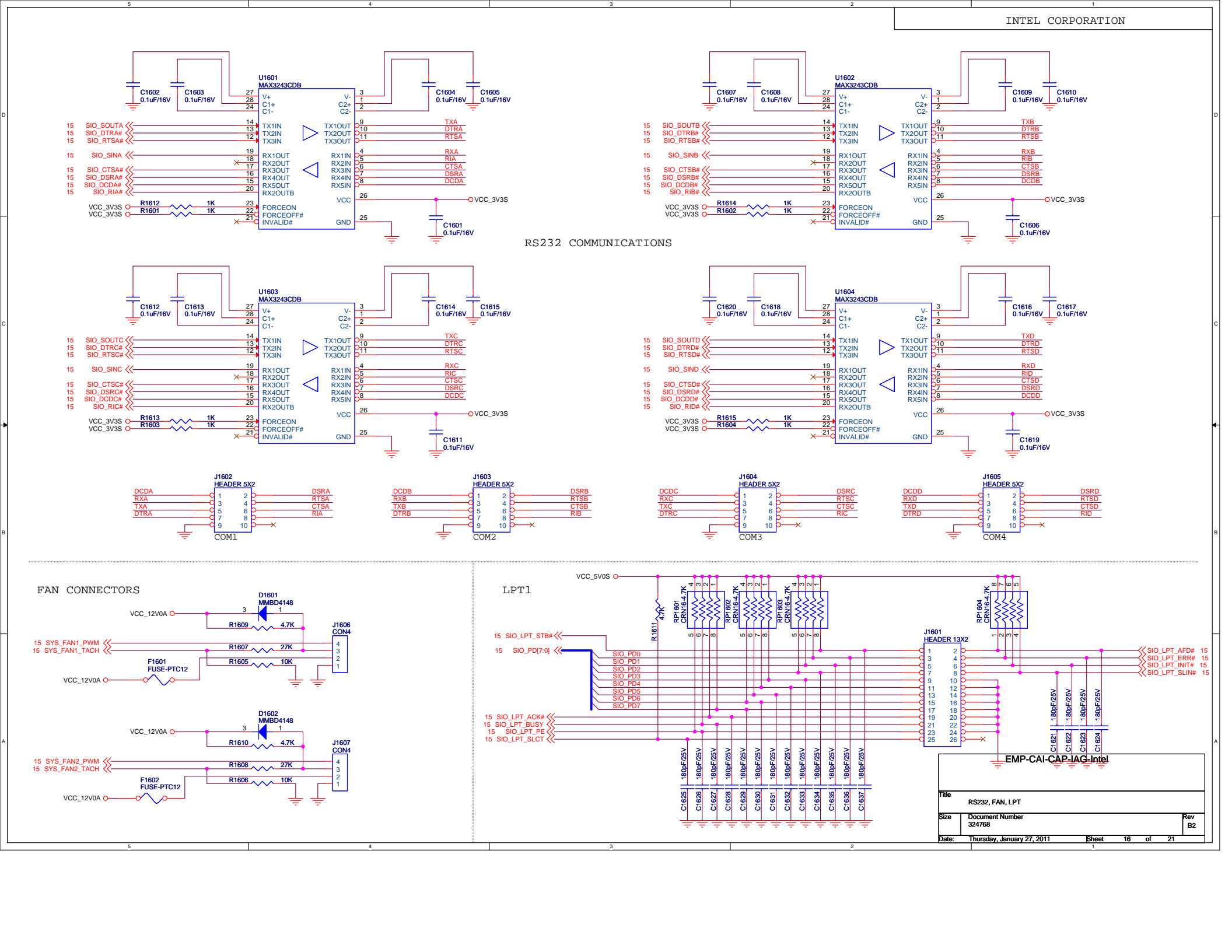
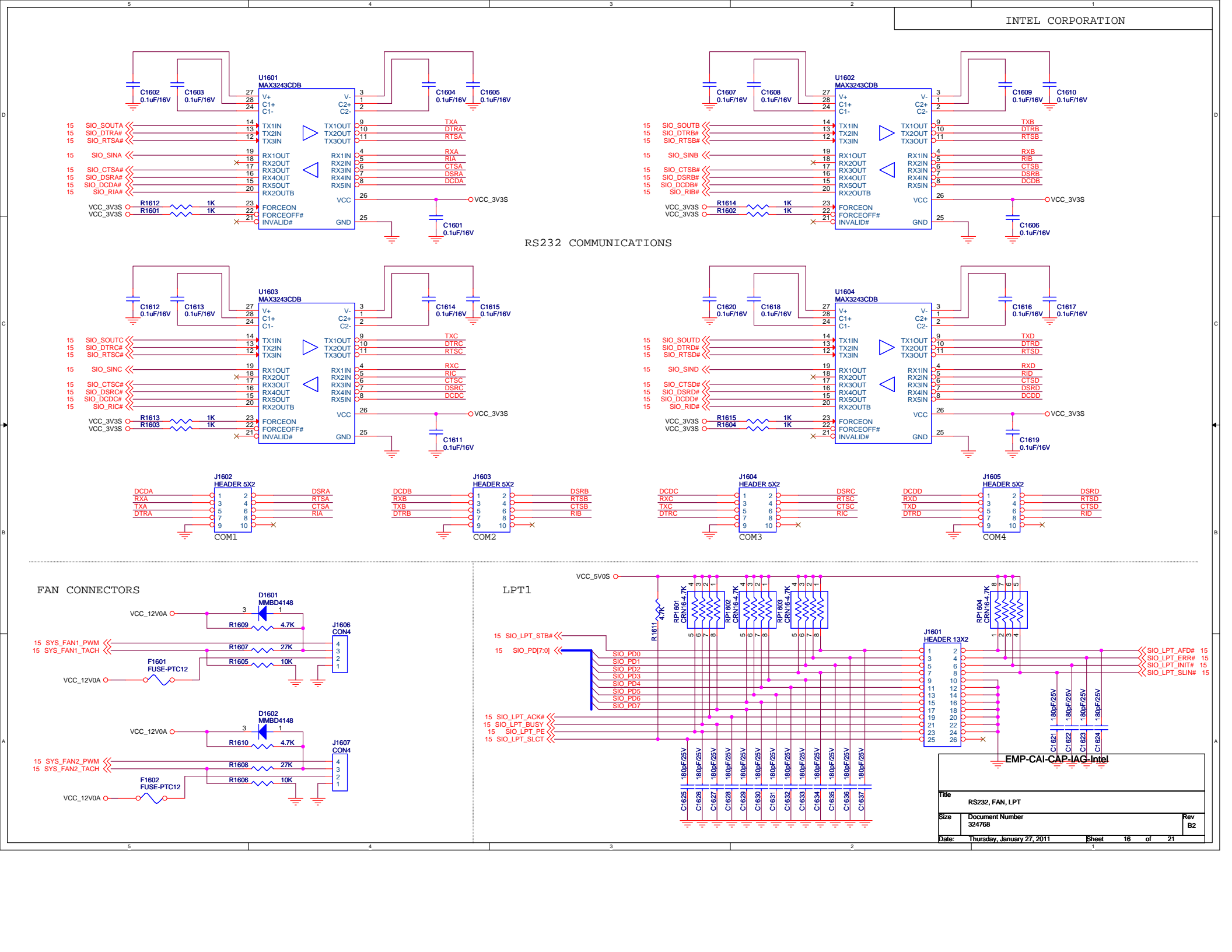
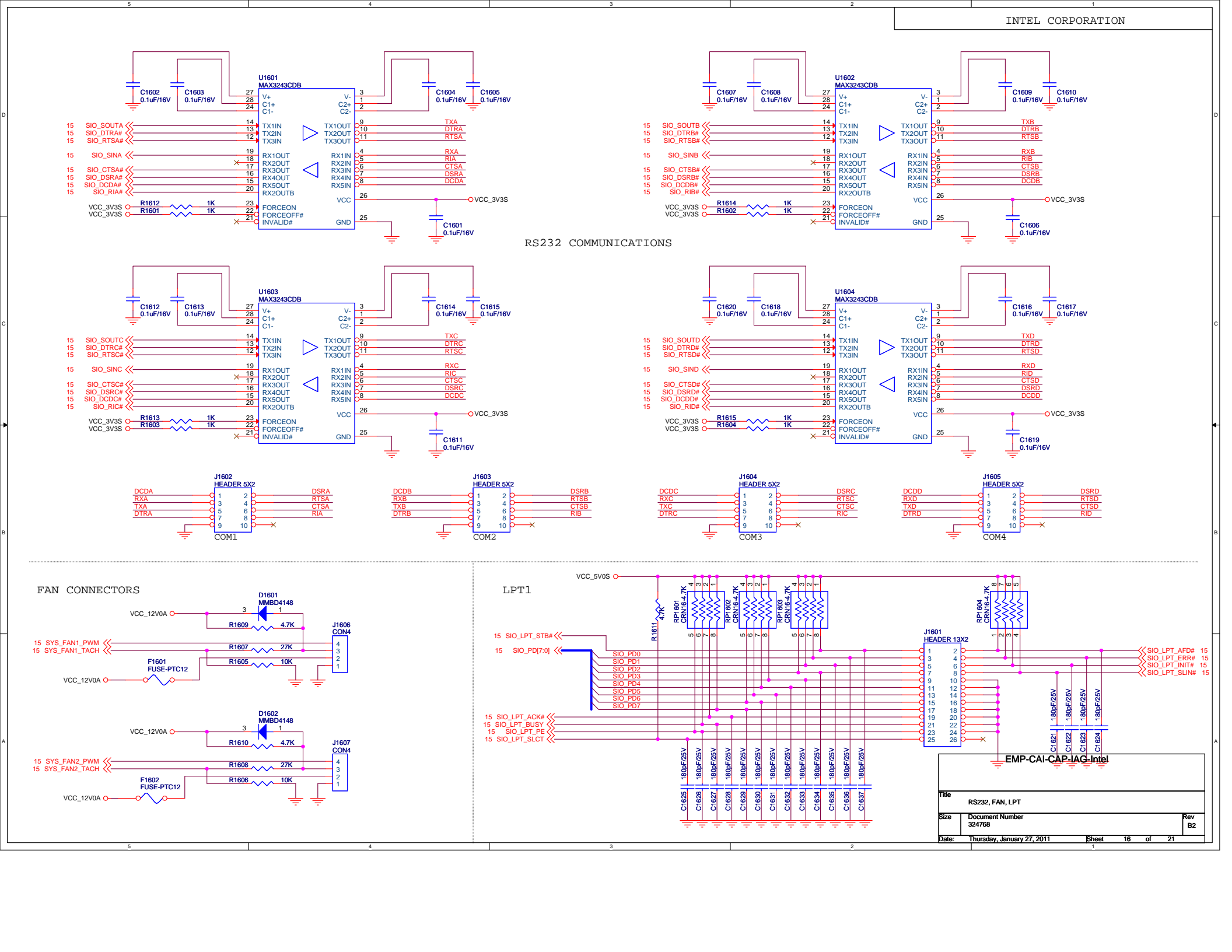
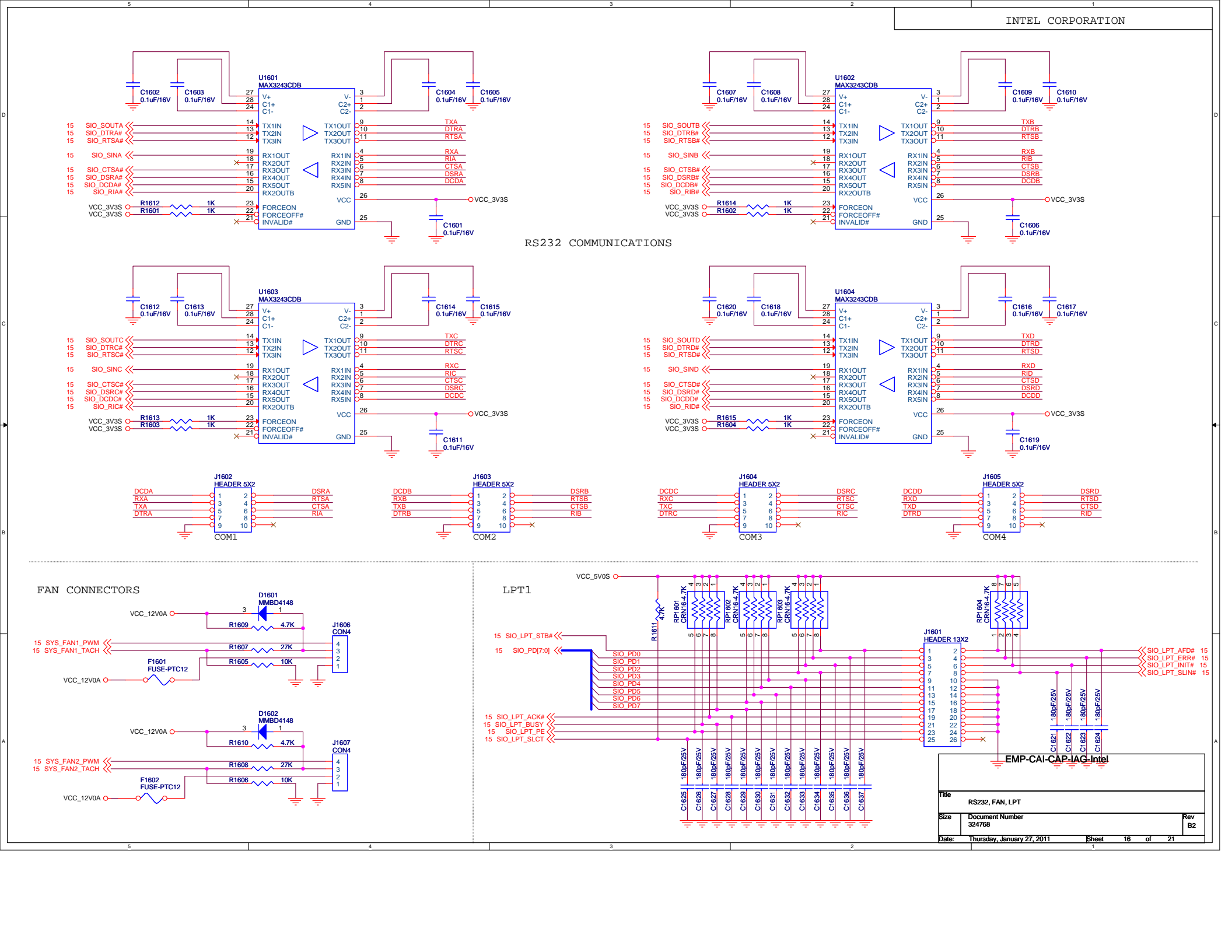
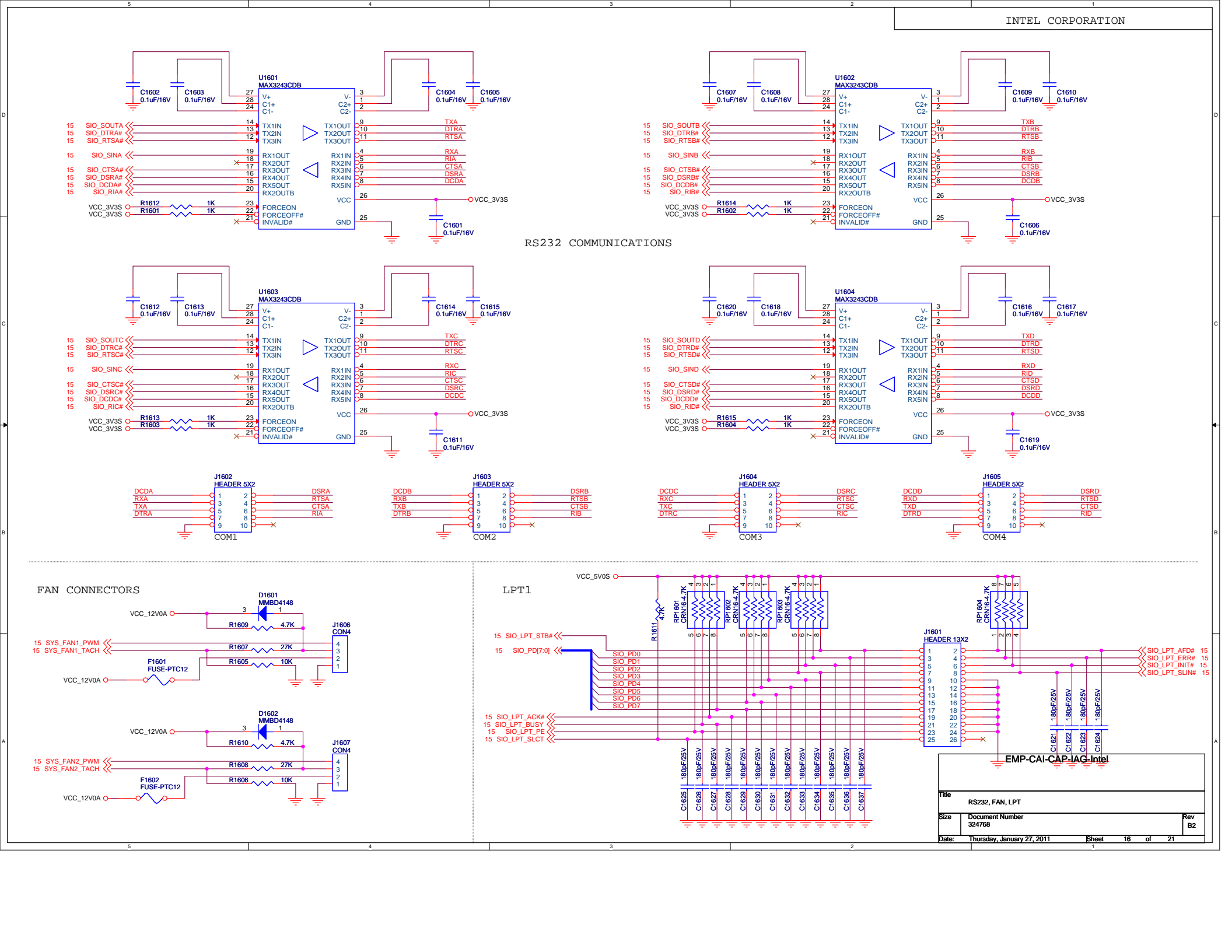
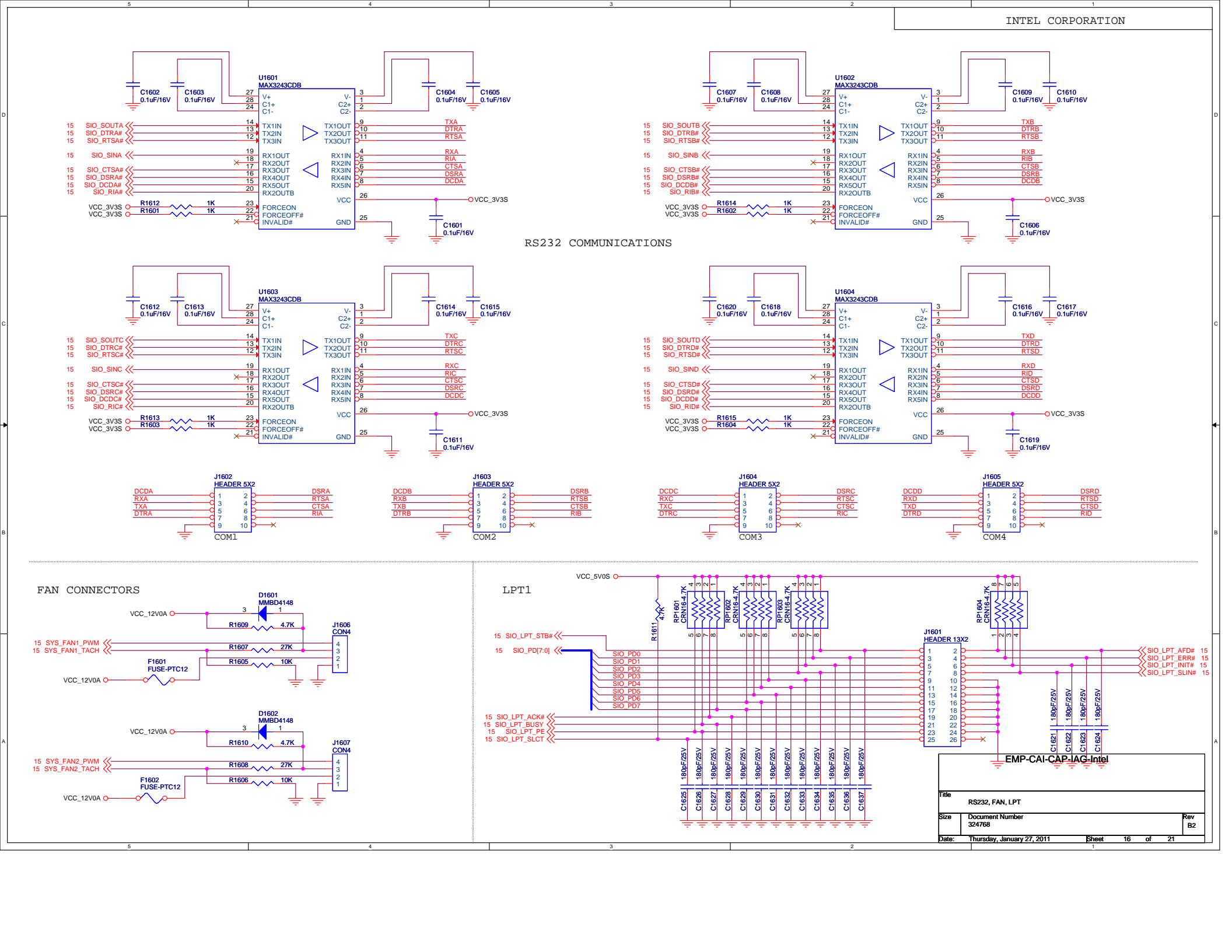
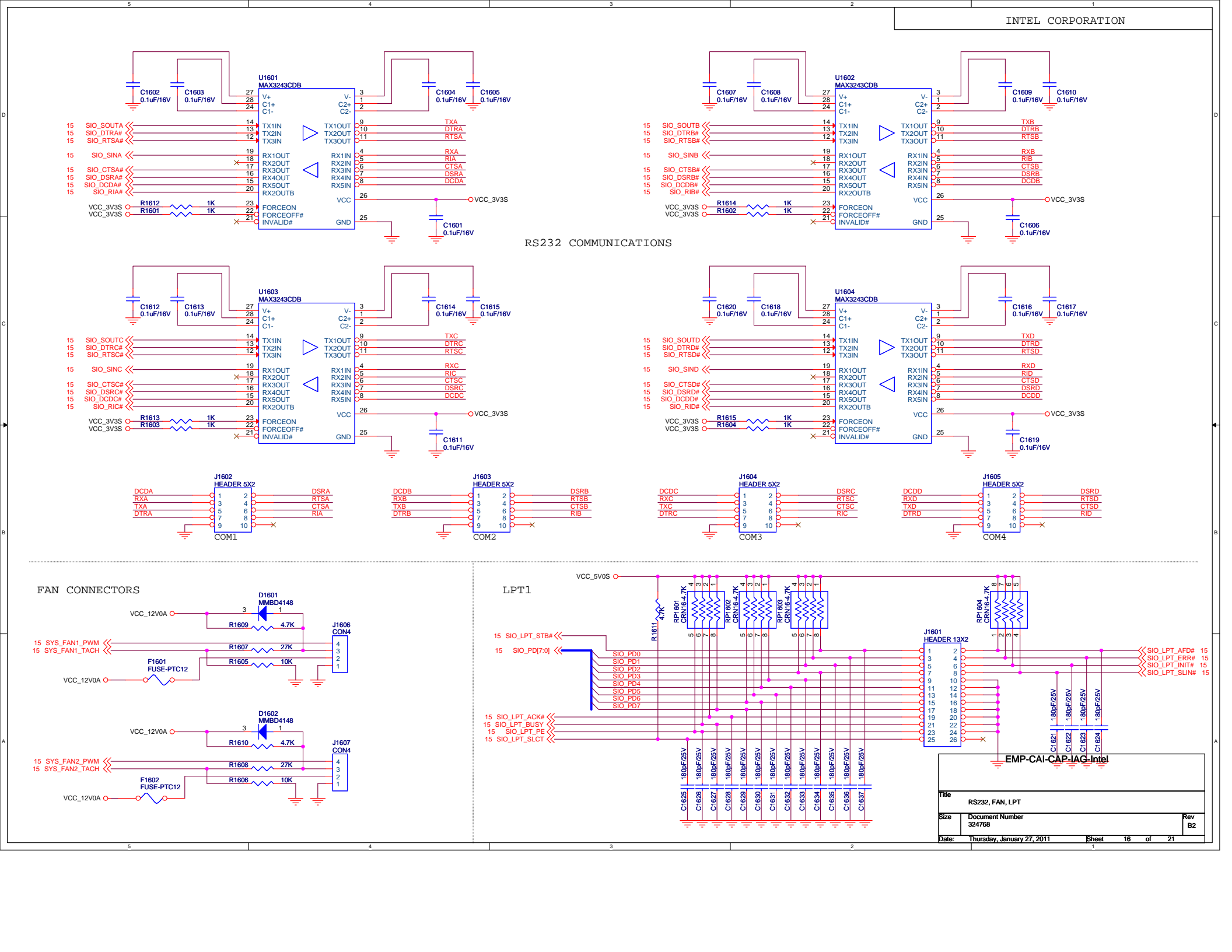
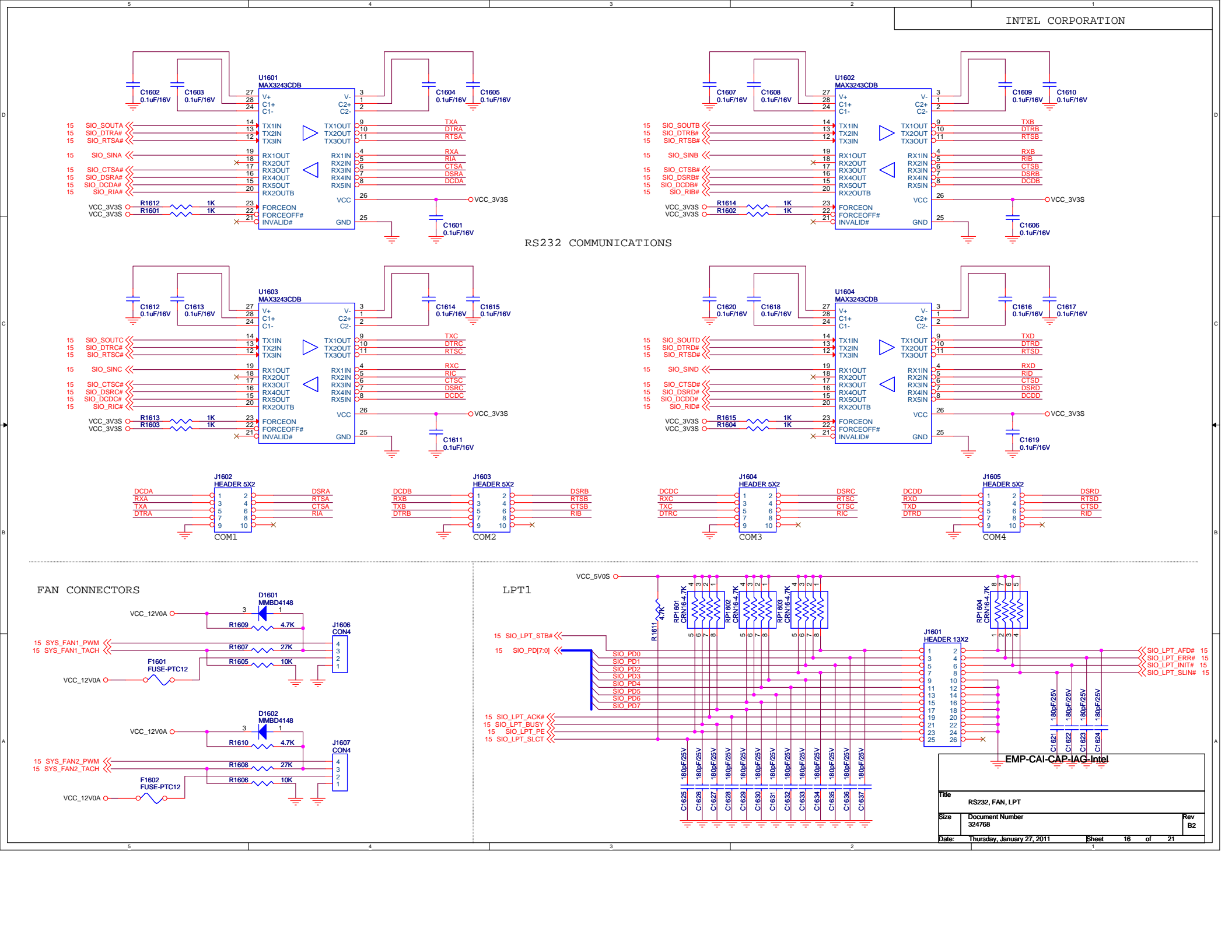
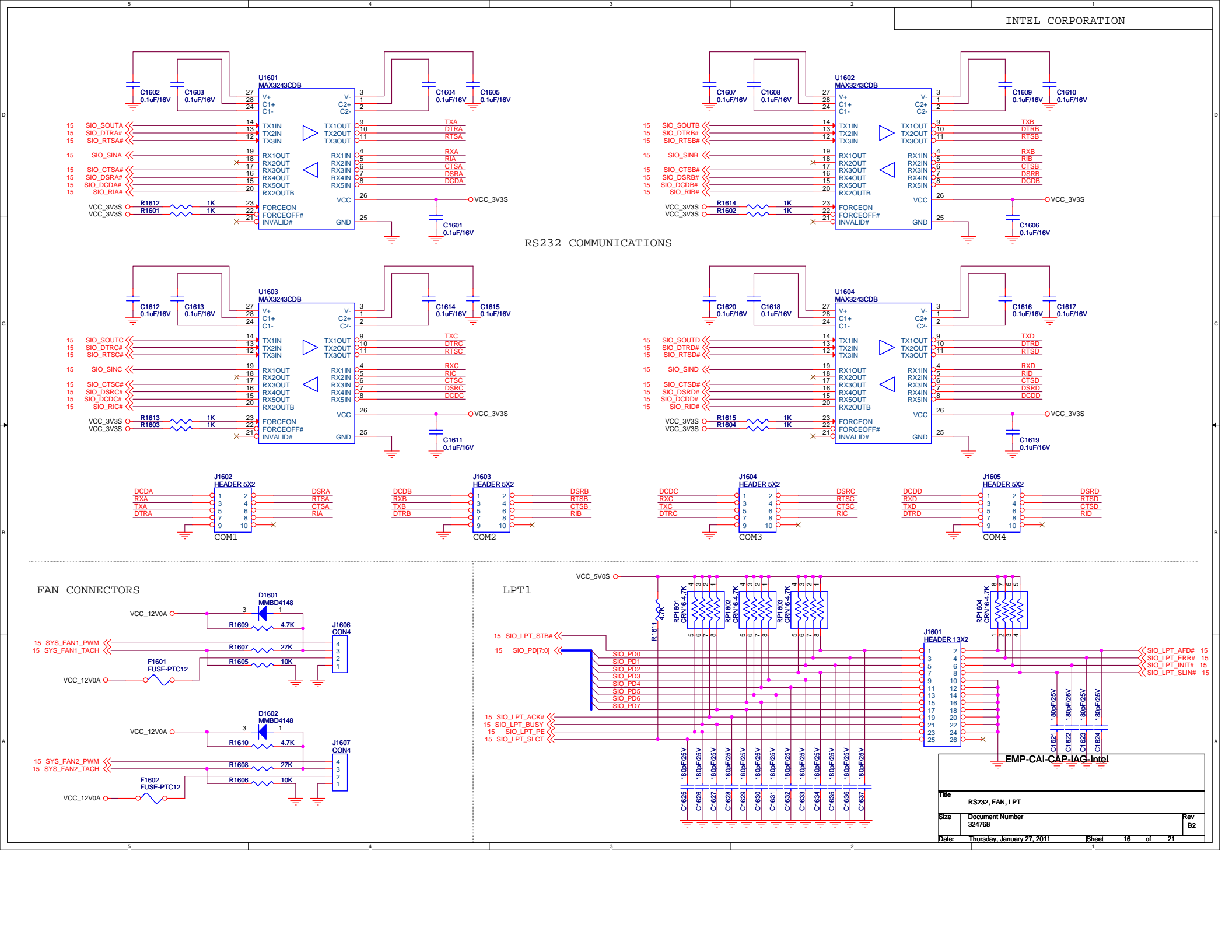
LPT1

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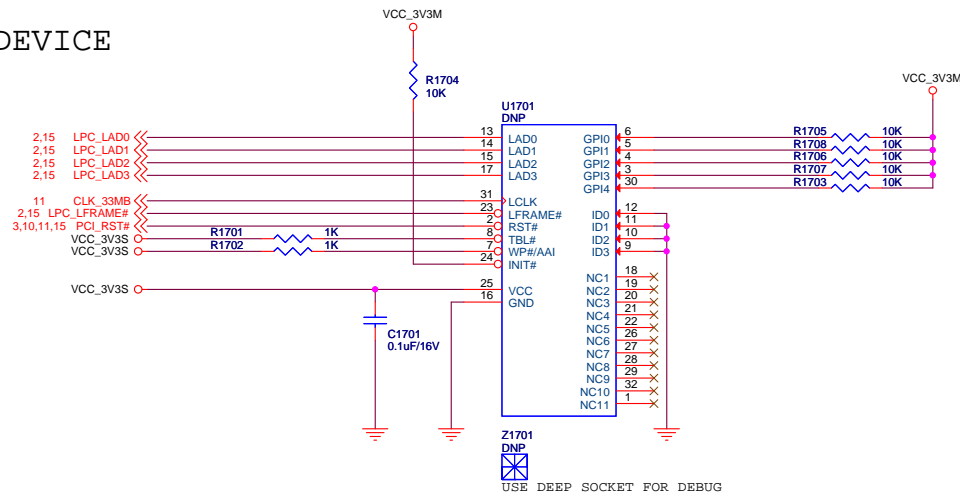
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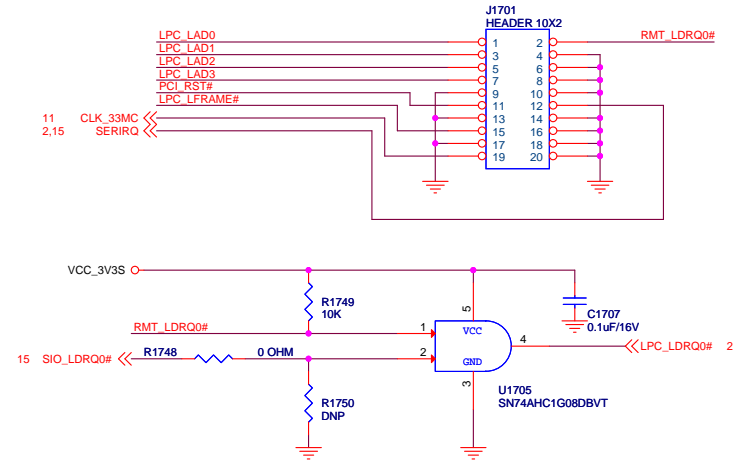
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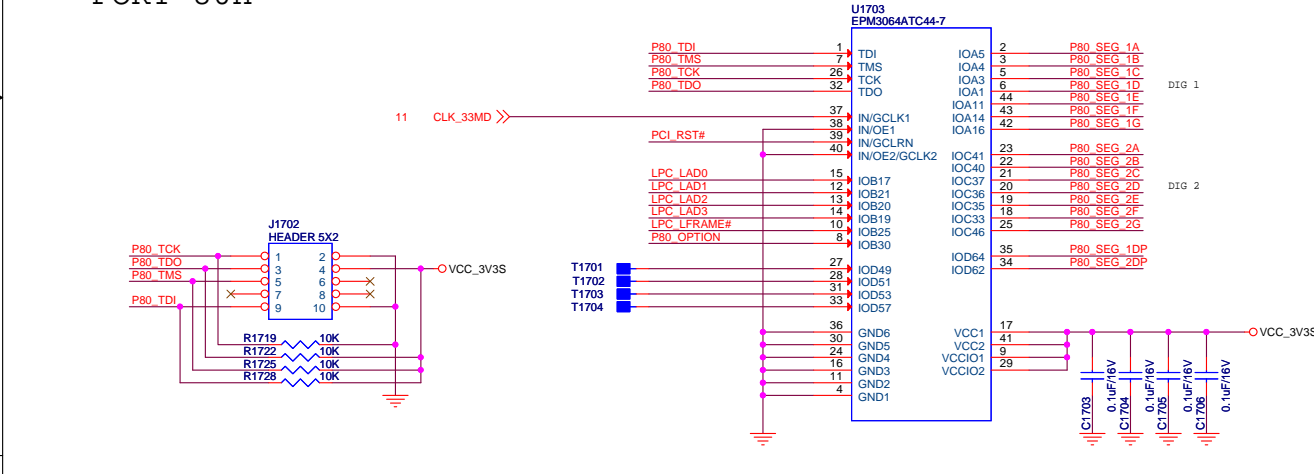
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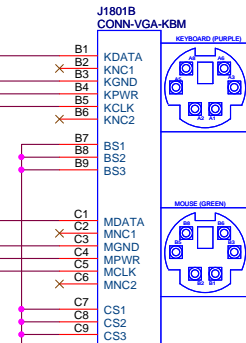
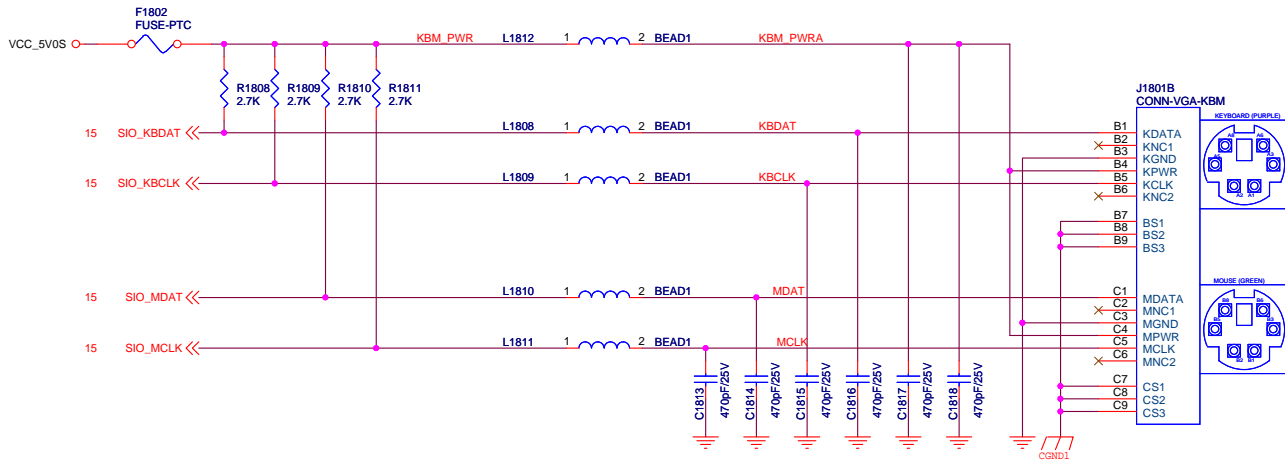


LPC CONNECTOR



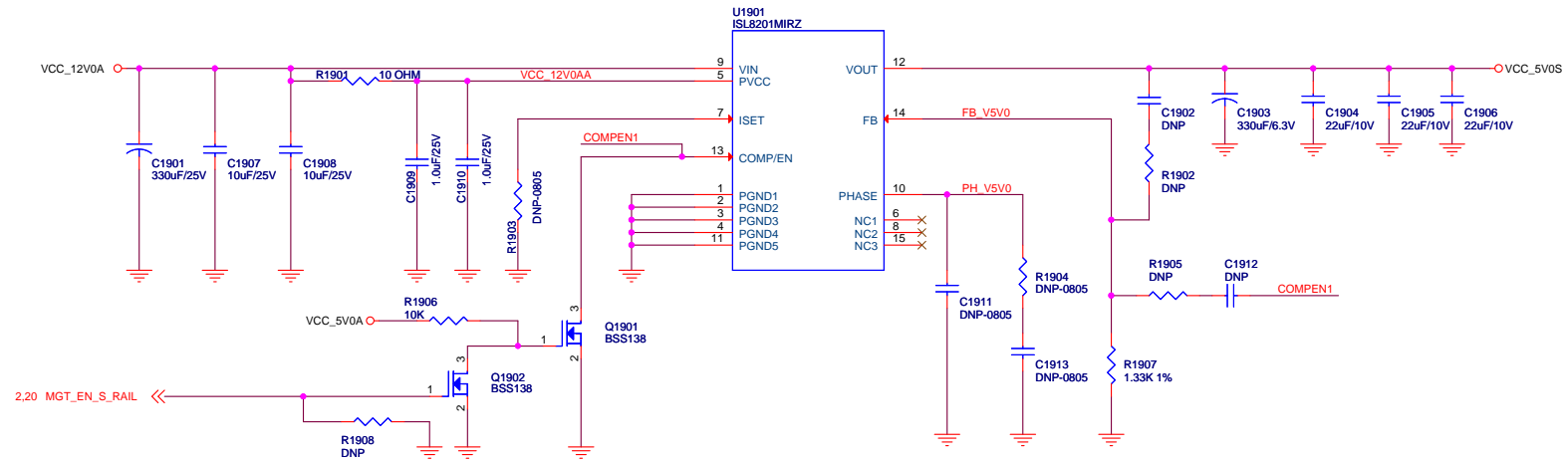
PORT 80H





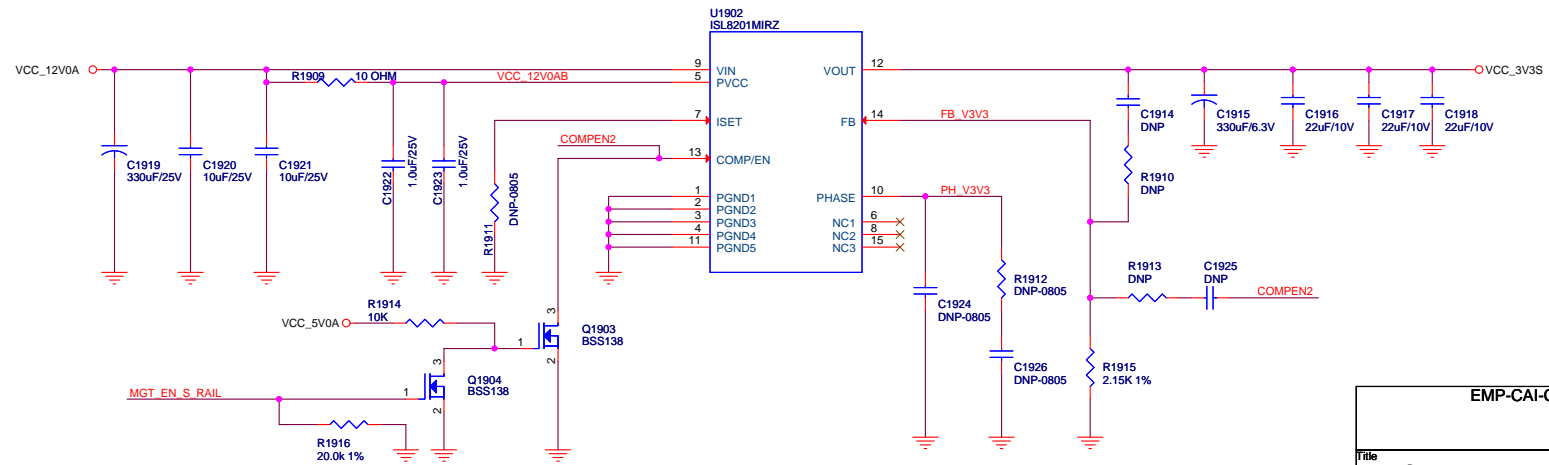
VCC 5.0 VDC 10 AMPS

MASTER



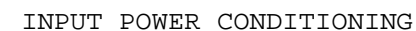
VCC 3.3 VDC 10 AMPS

MASTER



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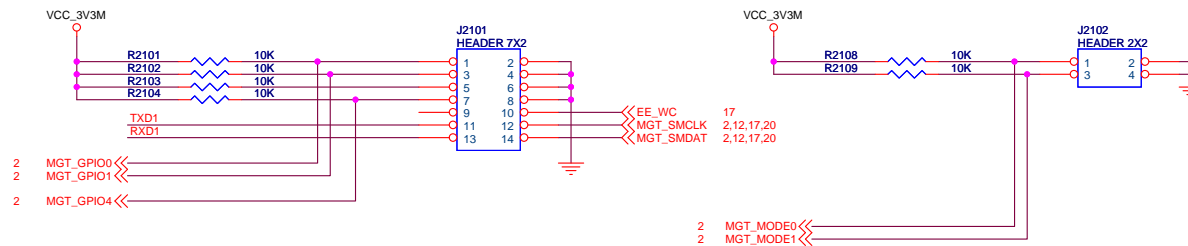
3.3VDC ALWAYS ON
500mA MAX

1.8VDC
500mA MAX

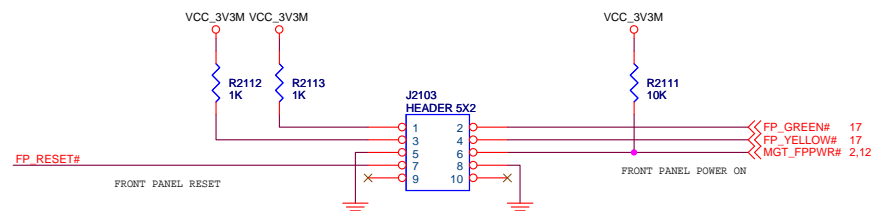
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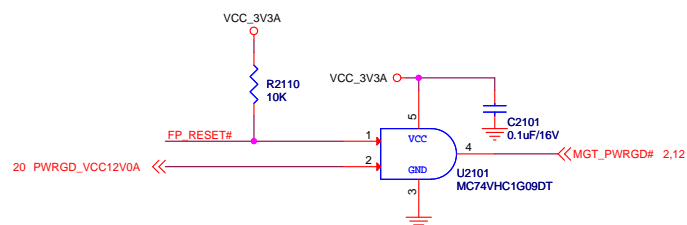
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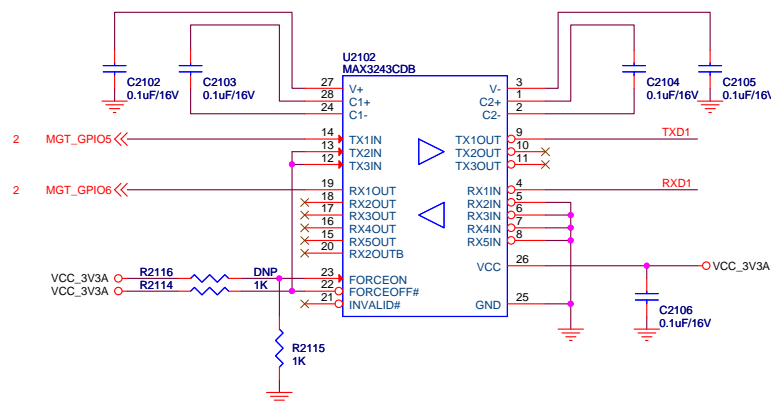
MODE SETUPS



FRONT PANEL SW



MANAGEMENT CONTROLLER SERIAL PORT



EMP-CAI-CAP-IAG-Intel

Title		
Mode, Front Panel Conn, Mangment Controller Serial Port		
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